

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	42445	enig (electroless with (nickel ni) with (immerse immersion immersed immersing) with (gold au))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 17:19
L2	944566	flipchip (flip adj3 chip) ball bump bga ((ball bump) adj3 grid adj4 array)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 17:12
L3	11727	1 with (substrate carrier board pcb ((printed wiring circuit) adj5 board))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 17:19
L4	1567	2 and 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 17:14
L5	515	bulk with solder	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 17:15
L6	2972	(pb lead) with (sn tin) with solder with (ball bump bga 2)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 17:17
L7	149	4 and 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 17:17
L8	6	5 and 7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 17:17

L9	513	enig (electroless with (nickel ni) with (immerse immersion immersed immersing) with (gold au))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 17:19
L10	74	9 with (substrate carrier board pcb ((printed wiring circuit) adj5 board))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 17:20
L11	29	10 and 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 17:20
L12	4	11 and 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 17:38
L13	1	"6288206".PN.	USPAT; USOCR	OR	OFF	2004/12/23 17:36
L14	1	"6307160".PN.	USPAT; USOCR	OR	OFF	2004/12/23 17:36
L15	1	"6445069".PN.	USPAT; USOCR	OR	OFF	2004/12/23 17:37
L16	1	"20020157241".PN.	US-PGPUB	OR	OFF	2004/12/23 17:37
L17	40906	(dope doping dopant doped) with (copper cu aluminum al ni nickel)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 17:39
L18	1	17 and 12	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 17:40
L19	1	11 and 18	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 17:40

L20	40905	17 not 18	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 17:41
L21	0	20 and 12	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 17:41
L22	0	20 and 11	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 17:41
L23	0	20 and 10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 17:41
L24	10	20 and 9	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 17:41

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	6649930	(copper cu aluminum al ni nickel)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 19:51
L2	2	"6286206".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 19:51
L3	1	1 and 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 20:02
L4	2	"6307160".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 20:02
L5	2	4 and 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 20:55
L6	1222571	aluminum	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 20:55
L7	2927	(pb lead) with (sn:tin) with solder with (ball:bump:bga)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 20:55
L8	104	7 with 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 20:58

L9	944566	flipchip (flip adj3 chip) ball bump bga ((ball bump) adj3 grid adj4 array)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 20:56
L10	42445	enig (electroless with (nickel ni) with (immerse immersion immersed immersing) with (gold au))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 20:56
L11	104	8 and 9	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 20:56
L12	15	10 and 11	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 20:57
L13	513	enig (electroless with (nickel ni) with (immerse immersion immersed immersing) with (gold au))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 20:59
L14	0	13 and 11	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 20:57
L15	0	8 and 13	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 20:58
L16	2378	enig (electroless with (nickel ni) and (immerse immersion immersed immersing) and (gold au))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 20:59

L17	1	16 and 8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 20:59
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